



DFN8L-3*3 物料成分表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition	CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English		
Die	0.64	Si	7440-21-3	100.00%
Lead Frame	9.27	Cu	7440-50-8	96.24-97.325
		Fe	7439-89-6	2.10~2.6
		Pb	7439-92-1	0.01MAX
		P	7723-14-0	0.015-0.15
		Zn	7440-66-6	0.05~0.2
		Ag	7440-22-4	0.5-0.8
Epoxy	0.22	Silver	7440-22-4	70-<90%
		bisphenol-F-(epichlorhydrin); epoxy resin (number average molecular weight ≤ 700)	9003-36-5	10-<20%
		butane	2425-79-8	3-<10%
		dapsone	80-08-0	1-<2.5%
Solder		Lead	7439-92-1	>= 70 -< 90
		Tin	7440-31-5	>= 1 -< 5
		Rosin,hydrogenated	65997-06-0	>= 2.5 -< 5
		Silver	7440-22-4	>= 1 -< 2.5
		Terpineol	8000-41-7	>= 1 -< 2.5
		2-(2-butoxyethoxy)ethanol	112-34-5	>= 1 -< 5
		other	-	>=0.35-<2
Wire		Copper	7440-50-8	≥99.99%
	Silver	7440-22-4	≤20ppm	
	other	/	≤25ppm	
	AL	7429-90-5	≥99.99%	
Mold Compound	Epoxy Resin A	Trade Secret	1 - 5	
	Epoxy Resin B	Trade Secret	1 - 5	
	Phenol Resin	Trade Secret	1 - 5	
	Silica(Amorphous)A	60676-86-0	70-90	
	Silica(Amorphous)B	7631-86-9	5-10	
	Carbon Black	1333-86-4	0.1 - 1	
Plating	Tin	7440-31-5	99.990%	
	other	/	0.010%	
Total	22.5			

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.